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S/N 10/826091

PATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	KAWAGUCHI, ET AL.	Examiner:	M. E. LAVILLA
Serial No.:	10/826091	Group Art Unit:	1775
Filed:	April 16, 2004	Docket No.:	10873.1436US01
Title:	BONDING LAYER FORMING SOLUTION, METHOD OF PRODUCING COPPER-TO-RESIN BONDING LAYER USING THE SOLUTION, AND LAYERED PRODUCT OBTAINED THEREBY		

CERTIFICATE UNDER 37 CFR 1.6(d)I hereby certify that this paper is being transmitted by facsimile to the U.S. Patent and Trademark Office on  
June 1, 2006By: 

Chieko Rogers

AMENDMENT AND RESPONSE

Mail Stop: AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Dear Sir:

In response to the Office Action dated March 3, 2006 and Advisory Action dated  
May 23, 2006, please amend the above-identified application as follows:

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 6 of this paper.

*OK to enter  
am  
6/16/06*